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09/678459  
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**PATENT NUMBER**

## **U.S. UTILITY Patent Application**

O.I.P.E.

**PATENT DATE**

SCANNED

SCANNED  BY 

APPLICATION NO. 09/678459	CONT/PRIOR D F	CLASS 438 225	SUBCLASS -	ART UNIT 2812	EXAMINER Smith
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MASUMITSU INO  
TOSHIKAZU MAEKAWA

## Process of fabricating thin film semiconductor device

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PTO-2040  
12/99

## ISSUING CLASSIFICATION

□ TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.				NOTICE OF ALLOWANCE MAILED	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____				ISSUE FEE	
				Amount Due	Date Paid
<input type="checkbox"/> The terminal ___ months of this patent have been disclaimed.				ISSUE BATCH NUMBER	

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